



Atty. Dkt. No. APPM/003421.C2/PPC/ECP/CKIM

Re Application of:  
Cheung, et al.

Group Art Unit: 1742

Examiner: Harry D. Wilkins, III

For: Apparatus for Electro  
Chemical Deposition of  
Copper Metallization with  
the Capability of In-Situ  
Thermal Annealing

CERTIFICATE OF MAILING  
37 CFR 1.8

I hereby certify that this correspondence is being deposited on 4/11, 2006 with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dear Sir:

4/11/06  
Date

  
Keith M. Tackett

**RESPONSE TO OFFICE ACTION DATED JANUARY 11, 2006**

In response to the Office Action dated January 11, 2006, having a shortened statutory period for response set to expire on April 11, 2006, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/003421.C2/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 6 of this paper.